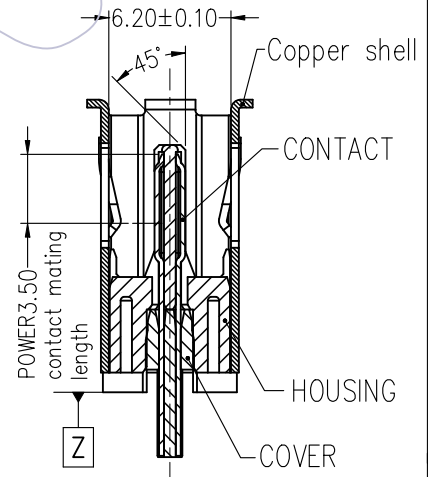
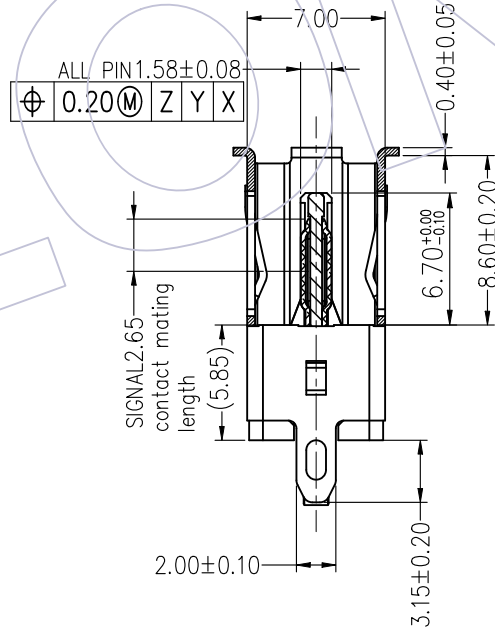
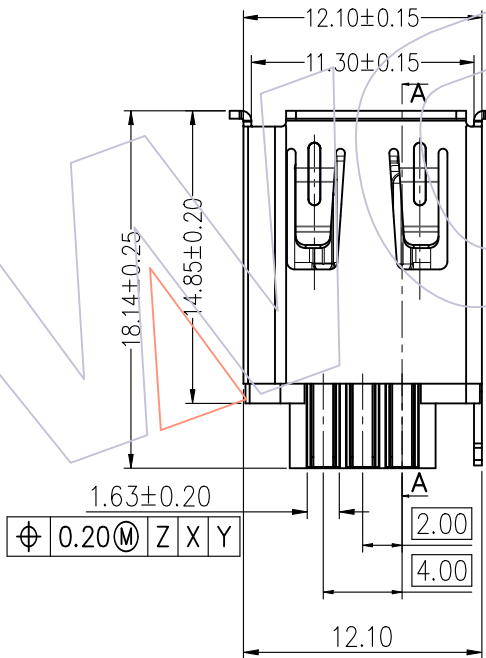
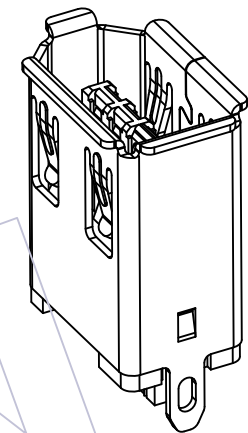
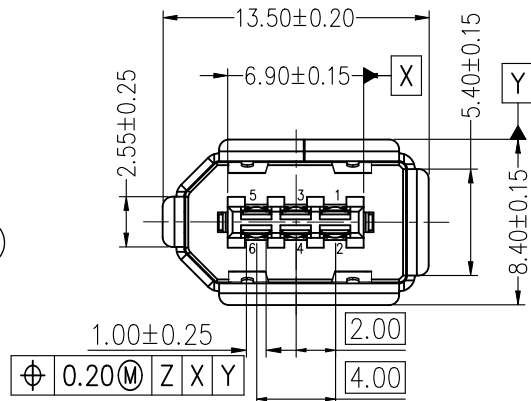


HSF

NOTES:

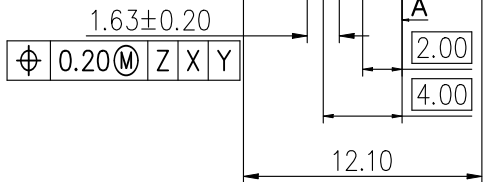
1. Material:
 - Housing/Cover: PBT UL94V-0 BK
 - Terminal/Shell: Copper Alloy
2. Terminal Plating:
 - XXu"Gold on Contact Area(see ordering information)
 - 80u"Min.Sn on Solder Tails area
 - 50u" Ni underplating overall
4. Specification:
 - 4.1 Rating
 - Rated Current:1.0A
 - 4.2 Electrical
 - Contact Resistance: 30mΩ max
 - Withstand Voltage: 500V AC
 - Insulation Resistance: 100MΩ min
5. Operation Temperature: -40°C to +85°C
6. Soldering: Solder temperature: 245±3°C
Solder time: 3-5 S
7. Wire Accommodation: 18AWG Max.



Ordering Information

6130-06 M H SX A B N A 1

- PIN 06=6P
- TYP M=Male
- Join Typ H=Solder
- Terminal Plating S0=Gold Flash/Tin, S1=3u"Gold/Tin
- Wcon Internal Code
- Package A=Tray
- Post N=W/O
- Insulator Color B=Black, A=PBT
- Plastic Material



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A0	2020/11/02	NEW	-----	x.x ±0.40	Morris	2020/11/02	UNIT mm	A4	6130-06MHSXABNA1
				x.xx ±0.25	CHECK	DATE	SIZE	1/2	TITLE: 2.0mm SIC Connector Male Solder Molding Type
				x.xxx ±0.15	APPROVE	DATE	SHEET		Customer NO.
				Angle ± 3°			PROJ.		
				DIM TOL					

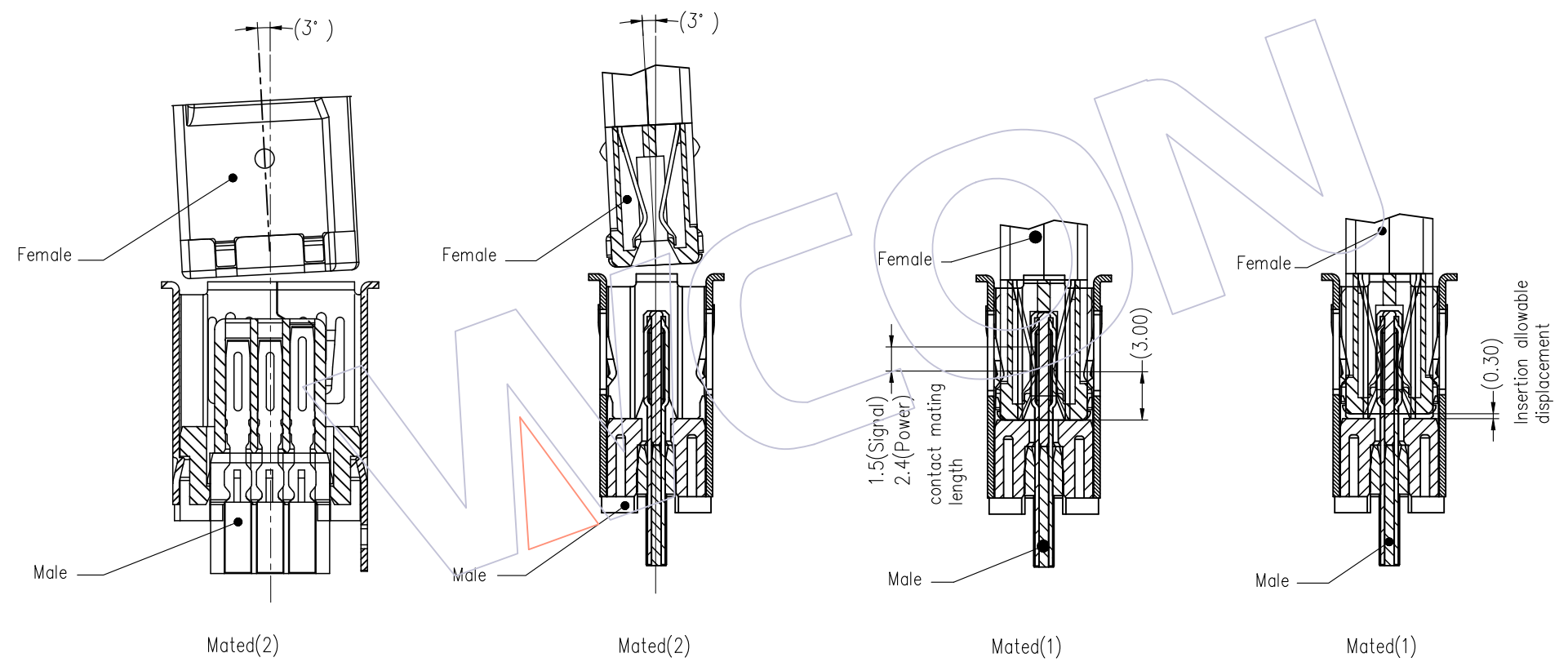
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HSF



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A0	2020/11/02	NEW	-----	x.X ±0.40	Morris	2020/11/02	UNIT	mm	6130-06MHSXABNA1
				x.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE: 2.0mm SIC Connector Male Solder Molding Type
				x.XXX ±0.15	APPROVE	DATE	SHEET	2/2	Customer NO.
				Angle ± 3°			PROJ.		
				DIM	TOL				

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